

Title (en)

METHOD FOR PRODUCING INSULATIONS OF ELECTRIC CONDUCTORS BY MEANS OF POWDER COATING

Title (de)

VERFAHREN ZUR HERSTELLUNG VON ISOLIERUNGEN ELEKTRISCHER LEITER MITTELS PULVERBESCHICHTUNG

Title (fr)

PROCEDE DE REALISATION D'ISOLATIONS DE CONDUCTEURS ELECTRIQUES PAR RECOUVREMENT AVEC UNE POUDRE

Publication

**EP 1250195 B1 20050907 (DE)**

Application

**EP 00982814 A 20001221**

Priority

- CH 0000683 W 20001221
- DE 19963378 A 19991228

Abstract (en)

[origin: WO0148763A2] The aim of the invention is to provide a method for producing insulations of electric conductors by means of powder coating which is characterized by an improved aging behavior compared to glass-mica or cast resin insulations and to also provide a powder appropriate for use in the inventive method. To this end, the powder is applied repeatedly up to a layer thickness of  $\leq 10$  mm in the form of subsequent individual layers and every individual layer is intermediately thermocured before the next individual layer is applied. The curing time observed for the intermediate curing of every individual layer corresponds to 2 to 10 times the gel time of the powder used. The entire insulating structure is then finally cured. The result of an electric life test of various test specimen, insulated with the epoxide resin powder that contains a fine filler and applied according to the inventive method, is shown in the only figure.

IPC 1-7

**B05D 1/06**; **B05D 7/00**; **B05D 5/12**; **H01B 3/30**; **H01B 3/40**

IPC 8 full level

**B05D 5/12** (2006.01); **B05D 1/02** (2006.01); **B05D 1/10** (2006.01); **B05D 1/24** (2006.01); **B05D 1/38** (2006.01); **B05D 7/24** (2006.01); **H01B 3/30** (2006.01); **H01B 3/40** (2006.01)

CPC (source: EP KR US)

**H01B 3/00** (2013.01 - KR); **H01B 3/30** (2013.01 - EP US); **H01B 3/40** (2013.01 - EP US); **Y10T 428/2982** (2015.01 - EP US)

Designated contracting state (EPC)

AT DE FR GB IT

DOCDB simple family (publication)

**WO 0148763 A2 20010705**; **WO 0148763 A3 20011220**; AT E303871 T1 20050915; AU 1980301 A 20010709; CN 1321749 C 20070620; CN 1437512 A 20030820; CZ 20022253 A3 20030312; DE 19963378 A1 20010712; DE 50011136 D1 20051013; EP 1250195 A2 20021023; EP 1250195 B1 20050907; JP 2003520664 A 20030708; KR 20020075387 A 20021004; RU 2002120489 A 20040220; US 2003113539 A1 20030619; US 6942900 B2 20050913

DOCDB simple family (application)

**CH 0000683 W 20001221**; AT 00982814 T 20001221; AU 1980301 A 20001221; CN 00819233 A 20001221; CZ 20022253 A 20001221; DE 19963378 A 19991228; DE 50011136 T 20001221; EP 00982814 A 20001221; JP 2001548397 A 20001221; KR 20027008519 A 20020628; RU 2002120489 A 20001221; US 16862502 A 20021112